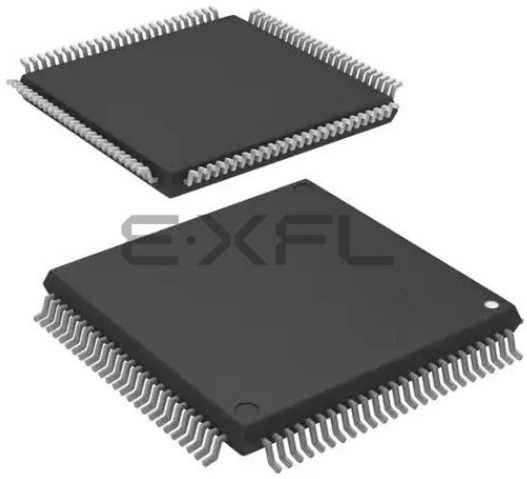

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	M16C/60
Core Size	16-Bit
Speed	24MHz
Connectivity	I²C, IEBus, UART/USART
Peripherals	DMA, WDT
Number of I/O	85
Program Memory Size	384KB (384K x 8)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	31K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 26x10b; D/A 2x8b
Oscillator Type	Internal
Operating Temperature	-20°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-LQFP
Supplier Device Package	100-LFQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/m30626fhpgpu5c-yr

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1. Overview

The M16C/62P Group (M16C/62P, M16C/62PT) of single-chip microcomputers are built using the high performance silicon gate CMOS process using a M16C/60 Series CPU core and are packaged in a 80-pin, 100-pin and 128-pin plastic molded QFP. These single-chip microcomputers operate using sophisticated instructions featuring a high level of instruction efficiency. With 1M bytes of address space, they are capable of executing instructions at high speed. In addition, this microcomputer contains a multiplier and DMAC which combined with fast instruction processing capability, makes it suitable for control of various OA, communication, and industrial equipment which requires high-speed arithmetic/logic operations.

1.1 Applications

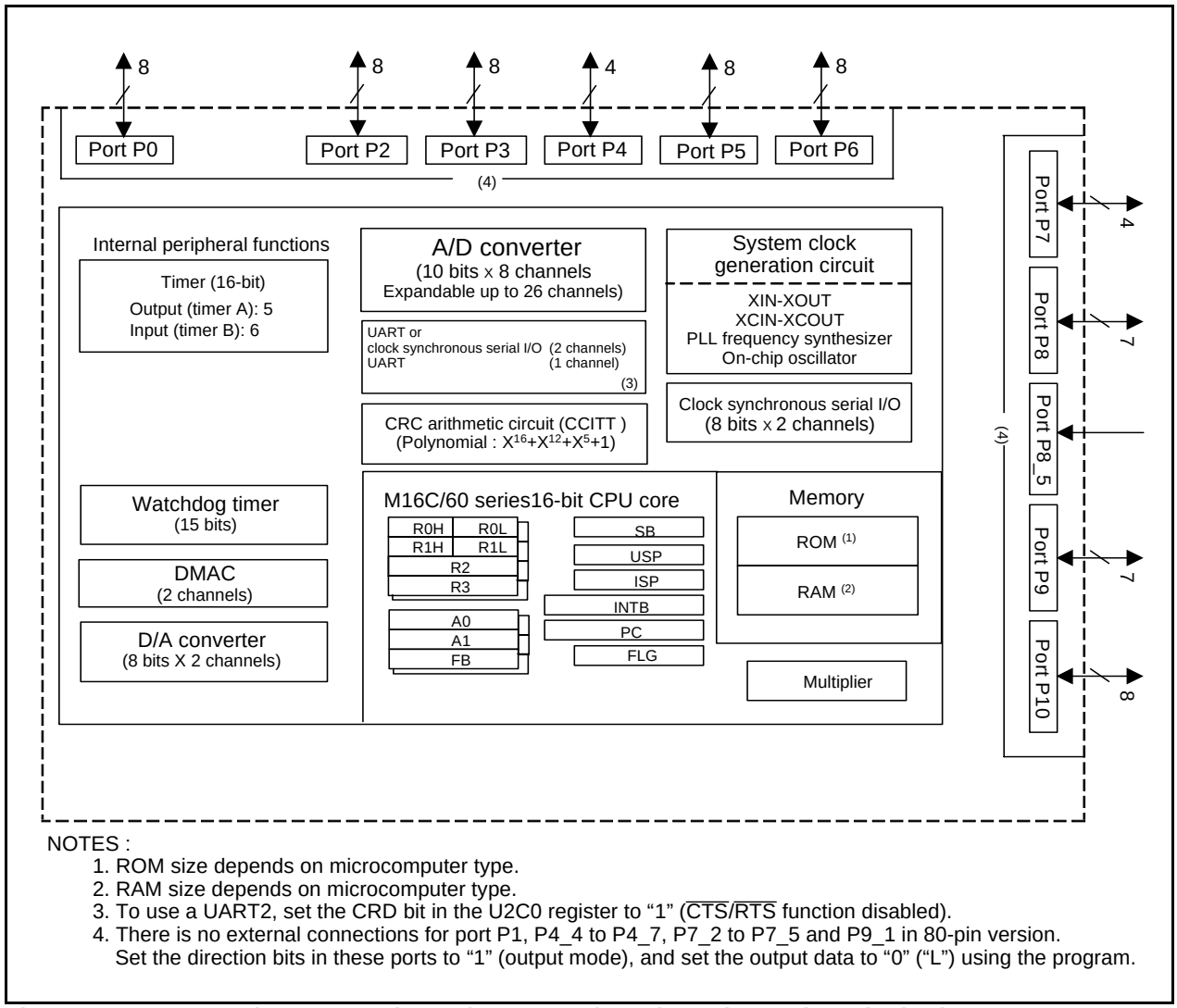
Audio, cameras, television, home appliance, office/communications/portable/industrial equipment, automobile, etc.

Specifications written in this manual are believed to be accurate, but are not guaranteed to be entirely free of error. Specifications in this manual may be changed for functional or performance improvements. Please make sure your manual is the latest edition.

Table 1.3 Performance Outline of M16C/62P Group (M16C/62P, M16C/62PT)(80-pin version)

	Item	Performance	
		M16C/62P	M16C/62PT(4)
CPU	Number of Basic Instructions	91 instructions	
	Minimum Instruction Execution Time	41.7ns(f(BCLK)=24MHz, VCC1=3.3 to 5.5V) 100ns(f(BCLK)=10MHz, VCC1=2.7 to 5.5V)	41.7ns(f(BCLK)=24MHz, VCC1=4.0 to 5.5V)
	Operating Mode	Single-chip mode	
	Address Space	1 Mbyte	
	Memory Capacity	See **Table 1.4 to 1.7 Product List**	
Peripheral Function	Port	Input/Output : 70 pins, Input : 1 pin	
	Multifunction Timer	Timer A : 16 bits x 5 channels (Timer A1 and A2 are internal timer), Timer B : 16 bits x 6 channels (Timer B1 is internal timer)	
	Serial Interface	2 channels Clock synchronous, UART, I2C bus(1), IEBus(2) 1 channel Clock synchronous, I2C bus(1), IEBus(2) 2 channels Clock synchronous (1 channel is only transmission)	
	A/D Converter	10-bit A/D converter: 1 circuit, 26 channels	
	D/A Converter	8 bits x 2 channels	
	DMAC	2 channels	
	CRC Calculation Circuit	CCITT-CRC	
	Watchdog Timer	15 bits x 1 channel (with prescaler)	
	Interrupt	Internal: 29 sources, External: 5 sources, Software: 4 sources, Priority level: 7 levels	
	Clock Generation Circuit	4 circuits Main clock generation circuit (*), Subclock generation circuit (*), On-chip oscillator, PLL synthesizer (*)Equipped with a built-in feedback resistor.	
	Oscillation Stop Detection Function	Stop detection of main clock oscillation, re-oscillation detection function	
	Voltage Detection Circuit	Available (option (4))	Absent
Electric Characteristics	Supply Voltage	VCC1=3.0 to 5.5 V, (f(BCLK=24MHz) VCC1=2.7 to 5.5 V, (f(BCLK=10MHz)	VCC1=4.0 to 5.5V, (f(BCLK=24MHz)
	Power Consumption	14 mA (VCC1=5V, f(BCLK)=24MHz) 8 mA (VCC1=3V, f(BCLK)=10MHz) 1.8μA (VCC1=3V, f(XCIN)=32kHz, wait mode) 0.7μA (VCC1=3V, stop mode)	14 mA (VCC1=5V, f(BCLK)=24MHz) 2.0μA (VCC1=5V, f(XCIN)=32kHz, wait mode) 0.8μA (VCC1=5V, stop mode)
Flash memory version	Program/Erase Supply Voltage	3.3 ± 0.3V or 5.0 ± 0.5V	5.0 ± 0.5V
	Program and Erase Endurance	100 times (all area) or 1,000 times (user ROM area without block A and block 1) / 10,000 times (block A, block 1) (3)	
Operating Ambient Temperature		-20 to 85°C, -40 to 85°C (3)	T version : -40 to 85°C V version : -40 to 125°C
Package		80-pin plastic mold QFP	

NOTES:
1. I2C bus is a registered trademark of Koninklijke Philips Electronics N. V.
2. IEBus is a registered trademark of NEC Electronics Corporation.
3. See **Table 1.8 and 1.9 Product Code** for the program and erase endurance, and operating ambient temperature.
   In addition 1,000 times/10,000 times are under development as of Jul., 2005. Please inquire about a release schedule.
4. All options are on request basis.



NOTES :
1. ROM size depends on microcomputer type.
2. RAM size depends on microcomputer type.
3. To use a UART2, set the CRD bit in the U2C0 register to “1” ($\overline{\text{CTS}}$/$\overline{\text{RTS}}$ function disabled).
4. There is no external connections for port P1, P4_4 to P4_7, P7_2 to P7_5 and P9_1 in 80-pin version. Set the direction bits in these ports to “1” (output mode), and set the output data to “0” (“L”) using the program.

Figure 1.2 M16C/62P Group (M16C/62P, M16C/62PT) 80-pin version Block Diagram

1.4 Product List

Table 1.4 to 1.7 list the product list, Figure 1.3 shows the Type No., Memory Size, and Package, Table 1.8 lists the Product Code of Flash Memory version and ROMless version for M16C/62P, and Table 1.9 lists the Product Code of Flash Memory version for M16C/62PT. Figure 1.4 shows the Marking Diagram of Flash Memory version and ROM-less version for M16C/62P (Top View), and Figure 1.5 shows the Marking Diagram of Flash Memory version for M16C/62PT (Top View) at the time of ROM order.

Table 1.4 Product List (1) (M16C/62P) As of Dec. 2005

Type No.	ROM Capacity	RAM Capacity	Package Type (1)	Remarks
M30622M6P-XXXFP	48 Kbytes	4 Kbytes	PRQP0100JB-A	Mask ROM version
M30622M6P-XXXGP			PLQP0100KB-A	
M30622M8P-XXXFP	64 Kbytes	4 Kbytes	PRQP0100JB-A	
M30622M8P-XXXGP			PLQP0100KB-A	
M30623M8P-XXXGP			PRQP0080JA-A	
M30622MAP-XXXFP	96 Kbytes	5 Kbytes	PRQP0100JB-A	
M30622MAP-XXXGP			PLQP0100KB-A	
M30623MAP-XXXGP			PRQP0080JA-A	
M30620MCP-XXXFP	128 Kbytes	10 Kbytes	PRQP0100JB-A	
M30620MCP-XXXGP			PLQP0100KB-A	
M30621MCP-XXXGP			PRQP0080JA-A	
M30622MEP-XXXFP	192 Kbytes	12 Kbytes	PRQP0100JB-A	
M30622MEP-XXXGP			PLQP0100KB-A	
M30623MEP-XXXGP			PLQP0128KB-A	
M30622MGP-XXXFP	256 Kbytes	12 Kbytes	PRQP0100JB-A	
M30622MGP-XXXGP			PLQP0100KB-A	
M30623MGP-XXXGP			PLQP0128KB-A	
M30624MGP-XXXFP		20 Kbytes	PRQP0100JB-A	
M30624MGP-XXXGP			PLQP0100KB-A	
M30625MGP-XXXGP			PLQP0128KB-A	
M30622MWP-XXXFP	320 Kbytes	16 Kbytes	PRQP0100JB-A	
M30622MWP-XXXGP			PLQP0100KB-A	
M30623MWP-XXXGP			PLQP0128KB-A	
M30624MWP-XXXFP		24 Kbytes	PRQP0100JB-A	
M30624MWP-XXXGP			PLQP0100KB-A	
M30625MWP-XXXGP			PLQP0128KB-A	
M30626MWP-XXXFP		31 Kbytes	PRQP0100JB-A	
M30626MWP-XXXGP			PLQP0100KB-A	
M30627MWP-XXXGP			PLQP0128KB-A	

(D): Under development

NOTES:

1. The old package type numbers of each package type are as follows.
   PLQP0128KB-A : 128P6Q-A,
   PRQP0100JB-A : 100P6S-A,
   PLQP0100KB-A : 100P6Q-A,
   PRQP0080JA-A : 80P6S-A

Table 1.10 Pin Characteristics for 128-Pin Package (1)

Pin No.	Control Pin	Port	Interrupt Pin	Timer Pin	UART Pin	Analog Pin	Bus Control Pin
1	VREF						
2	AVCC						
3		P9_7			SIN4	$\overline{\text{ADTRG}}$	
4		P9_6			SOUT4	ANEX1	
5		P9_5			CLK4	ANEX0	
6		P9_4		TB4IN		DA1	
7		P9_3		TB3IN		DA0	
8		P9_2		TB2IN	SOUT3		
9		P9_1		TB1IN	SIN3		
10		P9_0		TB0IN	CLK3		
11		P14_1					
12		P14_0					
13	BYTE						
14	CNVSS						
15	XCIN	P8_7					
16	XCOUT	P8_6					
17	$\overline{\text{RESET}}$						
18	XOUT						
19	VSS						
20	XIN						
21	VCC1						
22		P8_5	$\overline{\text{NMI}}$				
23		P8_4	$\overline{\text{INT2}}$	ZP			
24		P8_3	$\overline{\text{INT1}}$				
25		P8_2	$\overline{\text{INT0}}$				
26		P8_1		TA4IN/$\overline{\text{U}}$			
27		P8_0		TA4OUT/U			
28		P7_7		TA3IN			
29		P7_6		TA3OUT			
30		P7_5		TA2IN/$\overline{\text{W}}$			
31		P7_4		TA2OUT/W			
32		P7_3		TA1IN/$\overline{\text{V}}$	$\overline{\text{CTS2}}$/$\overline{\text{RTS2}}$		
33		P7_2		TA1OUT/V	CLK2		
34		P7_1		TA0IN/TB5IN	RXD2/SCL2		
35		P7_0		TA0OUT	TXD2/SDA2		
36		P6_7			TXD1/SDA1		
37	VCC1						
38		P6_6			RXD1/SCL1		
39	VSS						
40		P6_5			CLK1		
41		P6_4			$\overline{\text{CTS1}}$/$\overline{\text{RTS1}}$/$\overline{\text{CTS0}}$/CLKS1		
42		P6_3			TXD0/SDA0		
43		P6_2			RXD0/SCL0		
44		P6_1			CLK0		
45		P6_0			$\overline{\text{CTS0}}$/$\overline{\text{RTS0}}$		
46		P13_7					
47		P13_6					
48		P13_5					
49		P13_4					
50		P5_7					$\overline{\text{RDY}}$/CLKOUT

1.6 Pin Description

Table 1.17 Pin Description (100-pin and 128-pin Version) (1)

Signal Name	Pin Name	I/O Type	Power Supply(3)	Description
Power supply input	VCC1,VCC2 VSS	I	–	Apply 2.7 to 5.5 V to the VCC1 and VCC2 pins and 0 V to the VSS pin. The VCC apply condition is that VCC1 ≥ VCC2. (1, 2)
Analog power supply input	AVCC AVSS	I	VCC1	Applies the power supply for the A/D converter. Connect the AVCC pin to VCC1. Connect the AVSS pin to VSS.
Reset input	$\overline{\text{RESET}}$	I	VCC1	The microcomputer is in a reset state when applying “L” to the this pin.
CNVSS	CNVSS	I	VCC1	Switches processor mode. Connect this pin to VSS to when after a reset to start up in single-chip mode. Connect this pin to VCC1 to start up in microprocessor mode.
External data bus width select input	BYTE	I	VCC1	Switches the data bus in external memory space. The data bus is 16 bits long when the this pin is held "L" and 8 bits long when the this pin is held "H". Set it to either one. Connect this pin to VSS when an single-chip mode.
Bus control pins (4)	D0 to D7	I/O	VCC2	Inputs and outputs data (D0 to D7) when these pins are set as the separate bus.
	D8 to D15	I/O	VCC2	Inputs and outputs data (D8 to D15) when external 16-bit data bus is set as the separate bus.
	A0 to A19	O	VCC2	Output address bits (A0 to A19).
	A0/D0 to A7/D7	I/O	VCC2	Input and output data (D0 to D7) and output address bits (A0 to A7) by timesharing when external 8-bit data bus are set as the multiplexed bus.
	A1/D0 to A8/D7	I/O	VCC2	Input and output data (D0 to D7) and output address bits (A1 to A8) by timesharing when external 16-bit data bus are set as the multiplexed bus.
	$\overline{\text{CS0}}$ to $\overline{\text{CS3}}$	O	VCC2	Output $\overline{\text{CS0}}$ to $\overline{\text{CS3}}$ signals. $\overline{\text{CS0}}$ to $\overline{\text{CS3}}$ are chip-select signals to specify an external space.
	$\overline{\text{WRL}}$/$\overline{\text{WR}}$ $\overline{\text{WRH}}$/$\overline{\text{BHE}}$ $\overline{\text{RD}}$	O	VCC2	Output $\overline{\text{WRL}}$, $\overline{\text{WRH}}$, ($\overline{\text{WR}}$, $\overline{\text{BHE}}$), $\overline{\text{RD}}$ signals. $\overline{\text{WRL}}$ and $\overline{\text{WRH}}$ or $\overline{\text{BHE}}$ and $\overline{\text{WR}}$ can be switched by program. • $\overline{\text{WRL}}$, $\overline{\text{WRH}}$ and $\overline{\text{RD}}$ are selected The $\overline{\text{WRL}}$ signal becomes "L" by writing data to an even address in an external memory space. The $\overline{\text{WRH}}$ signal becomes "L" by writing data to an odd address in an external memory space. The $\overline{\text{RD}}$ pin signal becomes "L" by reading data in an external memory space. • $\overline{\text{WR}}$, $\overline{\text{BHE}}$ and $\overline{\text{RD}}$ are selected The $\overline{\text{WR}}$ signal becomes "L" by writing data in an external memory space. The $\overline{\text{RD}}$ signal becomes "L" by reading data in an external memory space. The $\overline{\text{BHE}}$ signal becomes "L" by accessing an odd address. Select $\overline{\text{WR}}$, $\overline{\text{BHE}}$ and $\overline{\text{RD}}$ for an external 8-bit data bus.
	ALE	O	VCC2	ALE is a signal to latch the address.
	$\overline{\text{HOLD}}$	I	VCC2	While the $\overline{\text{HOLD}}$ pin is held "L", the microcomputer is placed in a hold state.
	$\overline{\text{HLDA}}$	O	VCC2	In a hold state, $\overline{\text{HLDA}}$ outputs a "L" signal.
	$\overline{\text{RDY}}$	I	VCC2	While applying a "L" signal to the $\overline{\text{RDY}}$ pin, the microcomputer is placed in a wait state.

I : Input O : Output I/O : Input and output

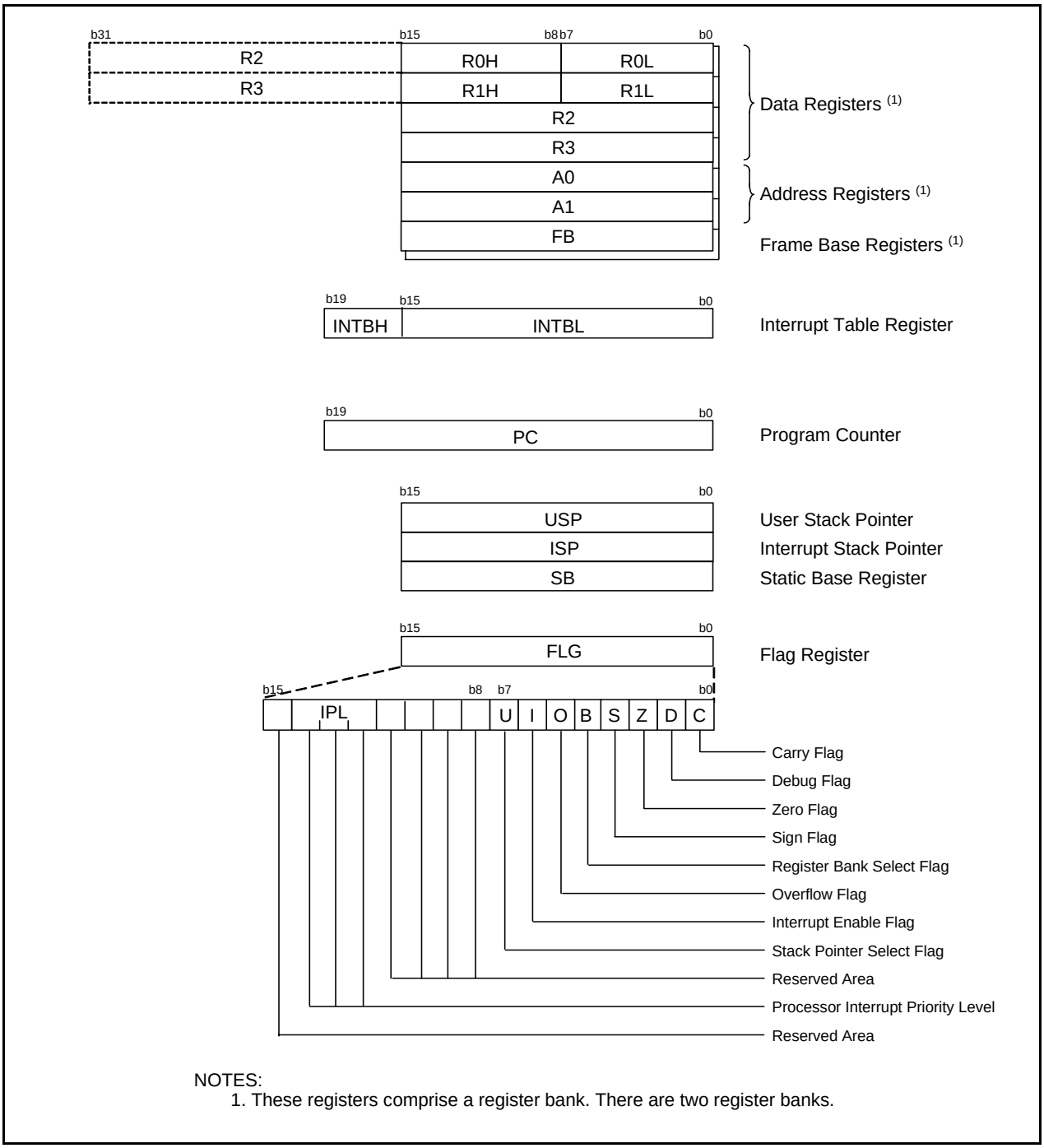
Power Supply : Power supplies which relate to the external bus pins are separated as VCC2, thus they can be interfaced using the different voltage as VCC1.

NOTES:

1. In this manual, hereafter, VCC refers to VCC1 unless otherwise noted.
2. In M16C/62PT, apply 4.0 to 5.5 V to the VCC1 and VCC2 pins. Also the apply condition is that VCC1 = VCC2.
3. When use VCC1 > VCC2, contacts due to some points or restrictions to be checked.
4. Bus control pins in M16C/62PT cannot be used.

2. Central Processing Unit (CPU)

Figure 2.1 shows the CPU registers. The CPU has 13 registers. Of these, R0, R1, R2, R3, A0, A1 and FB comprise a register bank. There are two register banks.



NOTES:
1. These registers comprise a register bank. There are two register banks.

Figure 2.1 Central Processing Unit Register

2.1 Data Registers (R0, R1, R2 and R3)

The R0 register consists of 16 bits, and is used mainly for transfers and arithmetic/logic operations. R1 to R3 are the same as R0.

The R0 register can be separated between high (R0H) and low (R0L) for use as two 8-bit data registers.

R1H and R1L are the same as R0H and R0L. Conversely, R2 and R0 can be combined for use as a 32-bit data register (R2R0). R3R1 is the same as R2R0.

2.2 Address Registers (A0 and A1)

The register A0 consists of 16 bits, and is used for address register indirect addressing and address register relative addressing. They also are used for transfers and logic/logic operations. A1 is the same as A0.
In some instructions, registers A1 and A0 can be combined for use as a 32-bit address register (A1A0).

2.3 Frame Base Register (FB)

FB is configured with 16 bits, and is used for FB relative addressing.

2.4 Interrupt Table Register (INTB)

INTB is configured with 20 bits, indicating the start address of an interrupt vector table.

2.5 Program Counter (PC)

PC is configured with 20 bits, indicating the address of an instruction to be executed.

2.6 User Stack Pointer (USP) and Interrupt Stack Pointer (ISP)

Stack pointer (SP) comes in two types: USP and ISP, each configured with 16 bits.
Your desired type of stack pointer (USP or ISP) can be selected by the U flag of FLG.

2.7 Static Base Register (SB)

SB is configured with 16 bits, and is used for SB relative addressing.

2.8 Flag Register (FLG)

FLG consists of 11 bits, indicating the CPU status.

2.8.1 Carry Flag (C Flag)

This flag retains a carry, borrow, or shift-out bit that has occurred in the arithmetic/logic unit.

2.8.2 Debug Flag (D Flag)

The D flag is used exclusively for debugging purpose. During normal use, it must be set to “0”.

2.8.3 Zero Flag (Z Flag)

This flag is set to “1” when an arithmetic operation resulted in 0; otherwise, it is “0”.

2.8.4 Sign Flag (S Flag)

This flag is set to “1” when an arithmetic operation resulted in a negative value; otherwise, it is “0”.

2.8.5 Register Bank Select Flag (B Flag)

Register bank 0 is selected when this flag is “0” ; register bank 1 is selected when this flag is “1”.

2.8.6 Overflow Flag (O Flag)

This flag is set to “1” when the operation resulted in an overflow; otherwise, it is “0”.

2.8.7 Interrupt Enable Flag (I Flag)

This flag enables a maskable interrupt.
Maskable interrupts are disabled when the I flag is “0”, and are enabled when the I flag is “1”. The I flag is cleared to “0” when the interrupt request is accepted.

$V_{CC1}=V_{CC2}=5V$

Switching Characteristics

(V_{CC1} = V_{CC2} = 5V, V_{SS} = 0V, at T_{opr} = –20 to 85°C / –40 to 85°C unless otherwise specified)

Table 5.28 Memory Expansion and Microprocessor Modes (for 1- to 3-wait setting and external area access)

Symbol	Parameter		Standard		Unit
			Min.	Max.	
$t_{d(BCLK-AD)}$	Address Output Delay Time	See **Figure 5.2**		25	ns
$t_{h(BCLK-AD)}$	Address Output Hold Time (in relation to BCLK)		4		ns
$t_{h(RD-AD)}$	Address Output Hold Time (in relation to RD)		0		ns
$t_{h(WR-AD)}$	Address Output Hold Time (in relation to WR)		(NOTE 2)		ns
$t_{d(BCLK-CS)}$	Chip Select Output Delay Time			25	ns
$t_{h(BCLK-CS)}$	Chip Select Output Hold Time (in relation to BCLK)		4		ns
$t_{d(BCLK-ALE)}$	ALE Signal Output Delay Time			15	ns
$t_{h(BCLK-ALE)}$	ALE Signal Output Hold Time		-4		ns
$t_{d(BCLK-RD)}$	RD Signal Output Delay Time			25	ns
$t_{h(BCLK-RD)}$	RD Signal Output Hold Time		0		ns
$t_{d(BCLK-WR)}$	WR Signal Output Delay Time			25	ns
$t_{h(BCLK-WR)}$	WR Signal Output Hold Time		0		ns
$t_{d(BCLK-DB)}$	Data Output Delay Time (in relation to BCLK)			40	ns
$t_{h(BCLK-DB)}$	Data Output Hold Time (in relation to BCLK) (3)		4		ns
$t_{d(DB-WR)}$	Data Output Delay Time (in relation to WR)		(NOTE 1)		ns
th(WR-DB)	Data Output Hold Time (in relation to WR)(3)		(NOTE 2)		ns
$t_{d(BCLK-HLDA)}$	HLDA Output Delay Time			40	ns

NOTES:

1. Calculated according to the BCLK frequency as follows:

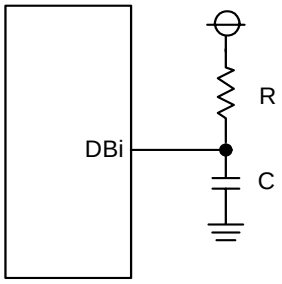
$$\frac{(n-0.5)\times 10^9}{f(BCLK)} - 40[ns]$$

n is “1” for 1-wait setting, “2” for 2-wait setting and “3” for 3-wait setting.
(BCLK) is 12.5MHz or less.

2. Calculated according to the BCLK frequency as follows:

$$\frac{0.5\times 10^9}{f(BCLK)} - 10[ns]$$

3. This standard value shows the timing when the output is off, and does not show hold time of data bus.
Hold time of data bus varies with capacitor volume and pull-up (pull-down) resistance value.
Hold time of data bus is expressed in
$t = -CR \times \ln(1 - V_{OL} / V_{CC2})$
by a circuit of the right figure.
For example, when V_{OL} = 0.2V_{CC2}, C = 30pF, R = 1kΩ, hold time of output ”L” level is
$t = -30pF \times 1k\Omega \times \ln(1 - 0.2V_{CC2} / V_{CC2})$
= 6.7ns.



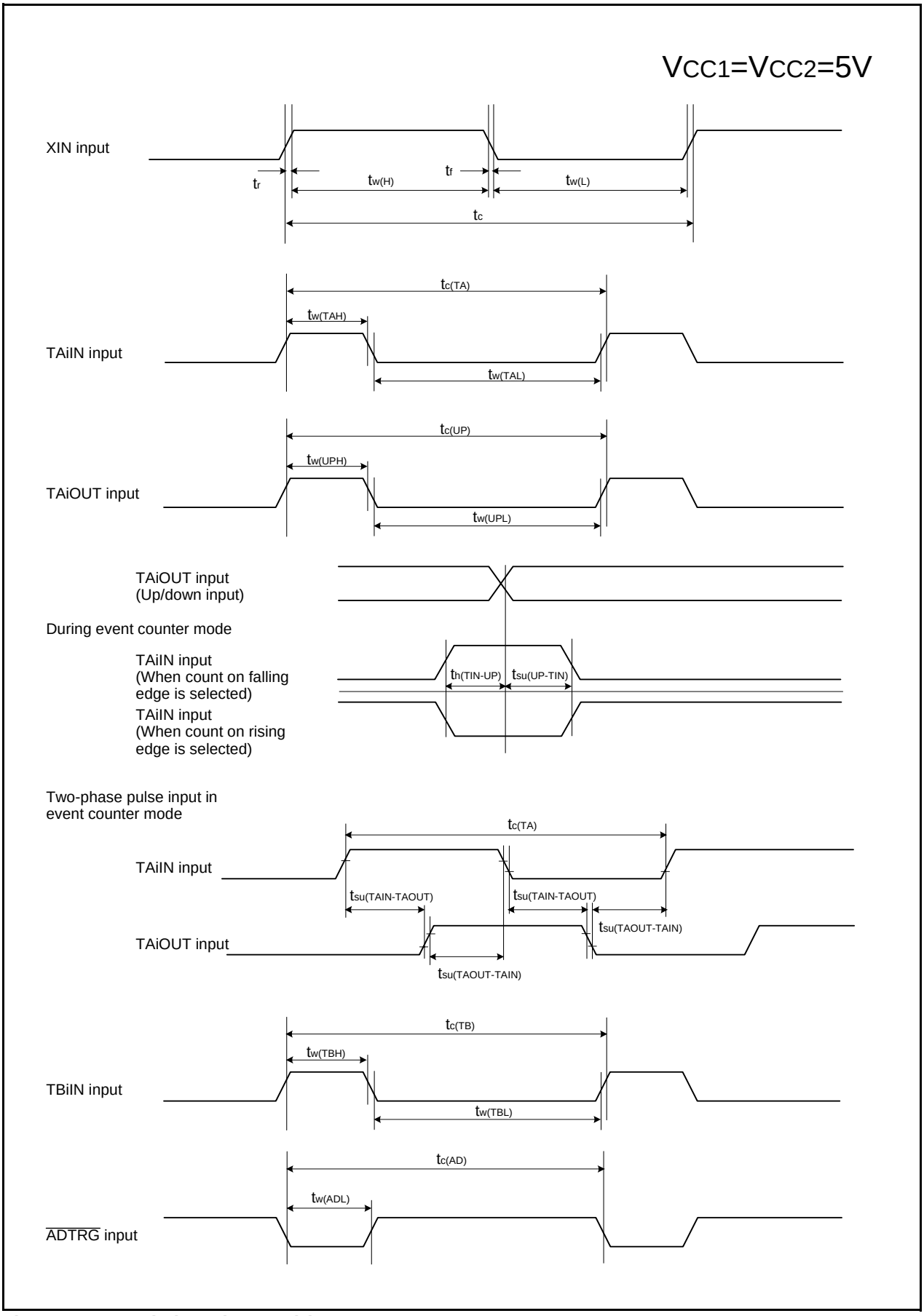
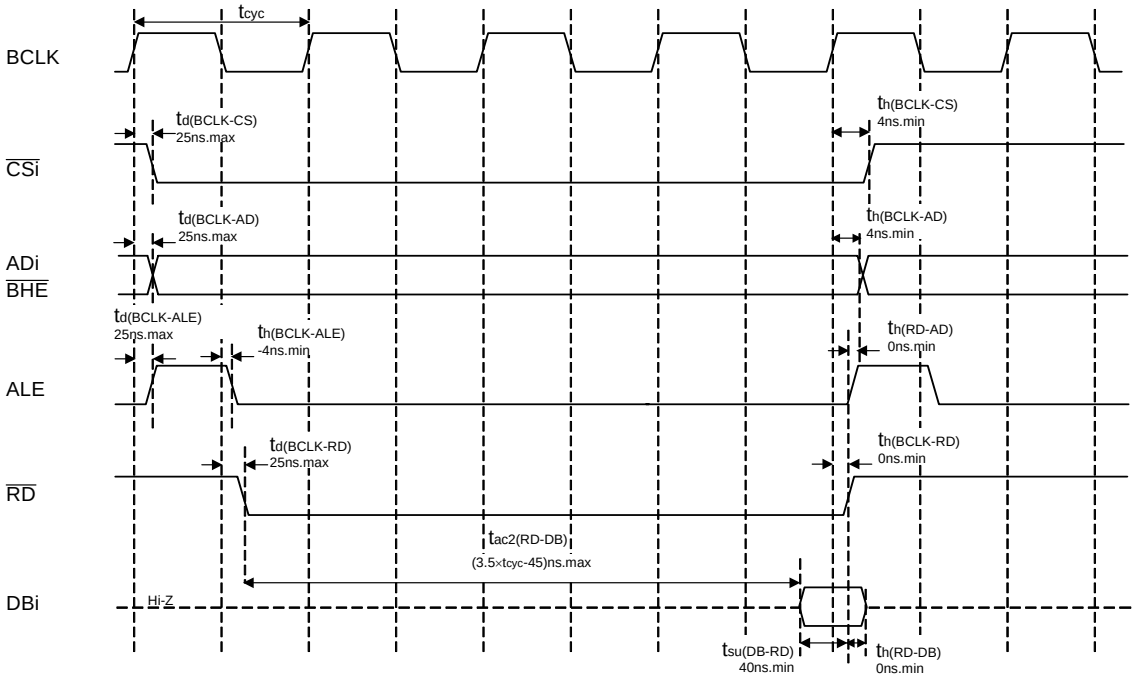


Figure 5.3 Timing Diagram (1)

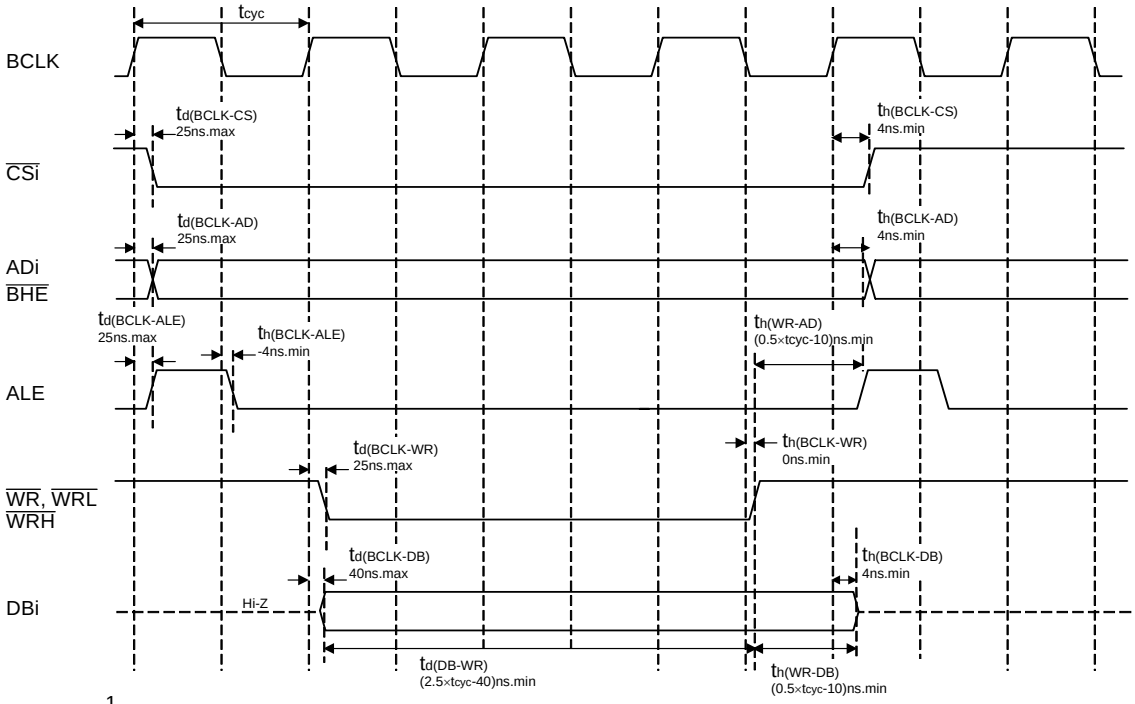
Memory Expansion Mode, Microprocessor Mode
(for 3-wait setting and external area access**)**

$V_{CC1}=V_{CC2}=5V$

Read timing



Write timing



$$t_{cyc}=\frac{1}{f(BCLK)}$$

Measuring conditions
· $V_{CC1}=V_{CC2}=5V$
· Input timing voltage : $V_{IL}=0.8V$, $V_{IH}=2.0V$
· Output timing voltage : $V_{OL}=0.4V$, $V_{OH}=2.4V$

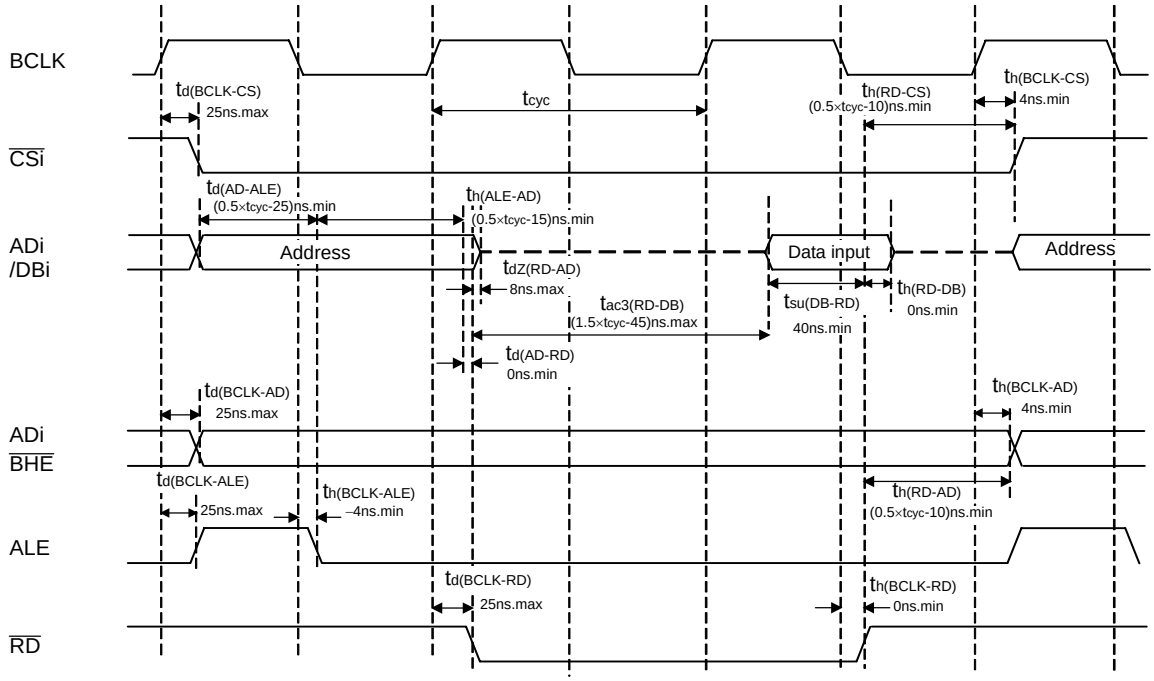
Figure 5.9 Timing Diagram (7)

$V_{CC1}=V_{CC2}=5V$

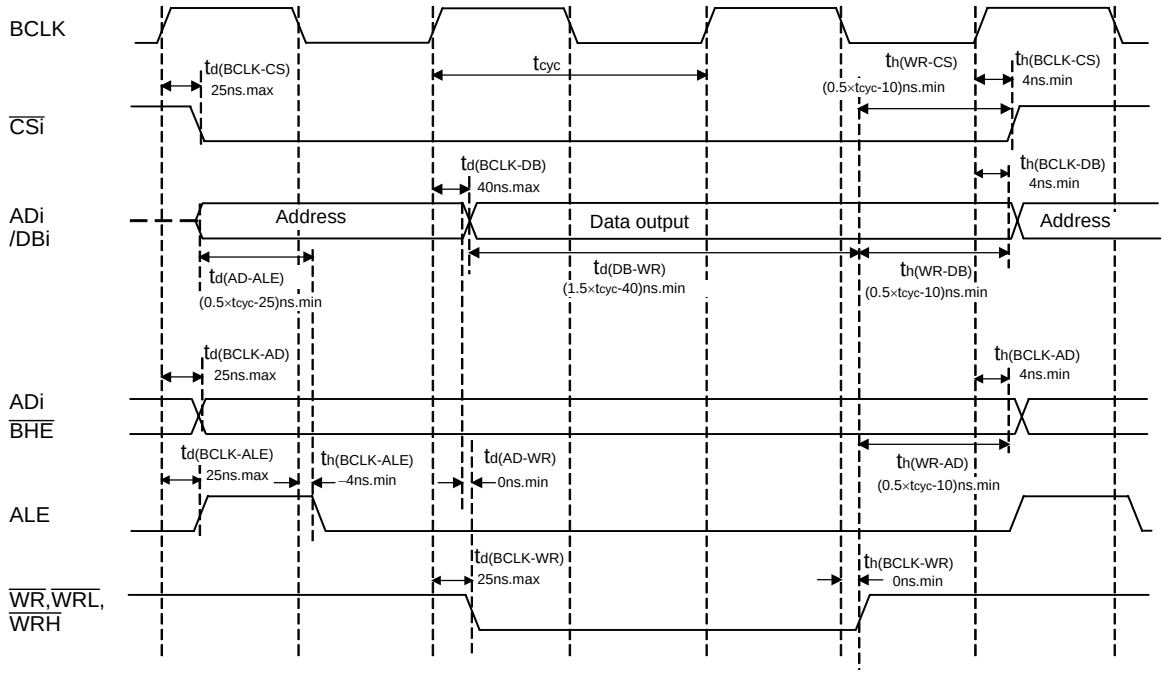
Memory Expansion Mode, Microprocessor Mode

(For 1- or 2-wait setting, external area access and multiplex bus selection**)**

Read timing



Write timing



Measuring conditions
· $V_{CC1}=V_{CC2}=5V$
· Input timing voltage : $V_{IL}=0.8V$, $V_{IH}=2.0V$
· Output timing voltage : $V_{OL}=0.4V$, $V_{OH}=2.4V$

Figure 5.10 Timing Diagram (8)

Table 5.31 Electrical Characteristics (2) (1)

Symbol	Parameter		Measuring Condition		Standard			Unit
					Min.	Typ.	Max.	
I_{CC}	Power Supply Current (V_{CC1}=V_{CC2}=2.7V to 3.6V)	In single-chip mode, the output pins are open and other pins are V_{SS}	Mask ROM	f(BCLK)=10MHz No division		8	11	mA
				No division, On-chip oscillation		1		mA
			Flash Memory	f(BCLK)=10MHz, No division		8	13	mA
				No division, On-chip oscillation		1.8		mA
			Flash Memory Program	f(BCLK)=10MHz, VCC1=3.0V		12		mA
			Flash Memory Erase	f(BCLK)=10MHz, VCC1=3.0V		22		mA
			Mask ROM	f(XCIN)=32kHz Low power dissipation mode, ROM (3)		25		µA
			Flash Memory	f(BCLK)=32kHz Low power dissipation mode, RAM (3)		25		µA
				f(BCLK)=32kHz Low power dissipation mode, Flash Memory (3)		420		µA
				On-chip oscillation, Wait mode		45		µA
			Mask ROM Flash Memory	f(BCLK)=32kHz Wait mode (2), Oscillation capability High		6.0		µA
				f(BCLK)=32kHz Wait mode (2), Oscillation capability Low		1.8		µA
				Stop mode Topr =25°C		0.7	3.0	µA
I_{det4}	Low Voltage Detection Dissipation Current (4)					0.6	4	µA
I_{det3}	Reset Area Detection Dissipation Current (4)					0.4	2	µA

NOTES:
1. Referenced to V_{CC1}=V_{CC2}=2.7 to 3.3V, V_{SS} = 0V at T_{opr} = –20 to 85°C / –40 to 85°C, f(BCLK)=10MHz unless otherwise specified.
2. With one timer operated using fC32.
3. This indicates the memory in which the program to be executed exists.
4. I_{det} is dissipation current when the following bit is set to “1” (detection circuit enabled).

   I_{det4}: VC27 bit in the VCR2 register

   I_{det3}: VC26 bit in the VCR2 register

$V_{CC1}=V_{CC2}=3V$

Timing Requirements
(V_{CC1} = V_{CC2} = 3V, V_{SS} = 0V, at T_{opr} = –20 to 85°C / –40 to 85°C unless otherwise specified)

Table 5.32 External Clock Input (XIN input)(1)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
t_c	External Clock Input Cycle Time	(NOTE 2)		ns
$t_{w(H)}$	External Clock Input HIGH Pulse Width	(NOTE 3)		ns
$t_{w(L)}$	External Clock Input LOW Pulse Width	(NOTE 3)		ns
t_r	External Clock Rise Time		(NOTE 4)	ns
t_f	External Clock Fall Time		(NOTE 4)	ns

NOTES:
1. The condition is V_{CC1}=V_{CC2}=2.7 to 3.0V.
2. Calculated according to the V_{CC1} voltage as follows:

$$\frac{10^{-6}}{20 \times V_{CC2} - 44} \text{ [ns]}$$

3. Calculated according to the V_{CC1} voltage as follows:

$$\frac{10^{-6}}{20 \times V_{CC1} - 44} \times 0.4 \text{ [ns]}$$

4. Calculated according to the V_{CC1} voltage as follows:

$$-10 \times V_{CC1} + 45 \text{ [ns]}$$

Table 5.33 Memory Expansion Mode and Microprocessor Mode

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{ac1(RD-DB)}$	Data Input Access Time (for setting with no wait)		(NOTE 1)	ns
$t_{ac2(RD-DB)}$	Data Input Access Time (for setting with wait)		(NOTE 2)	ns
$t_{ac3(RD-DB)}$	Data Input Access Time (when accessing multiplex bus area)		(NOTE 3)	ns
$t_{su(DB-RD)}$	Data Input Setup Time	50		ns
$t_{su(RDY-BCLK)}$	$\overline{RDY}$ Input Setup Time	40		ns
$t_{su(HOLD-BCLK)}$	$\overline{HOLD}$ Input Setup Time	50		ns
$t_{h(RD-DB)}$	Data Input Hold Time	0		ns
$t_{h(BCLK-RDY)}$	$\overline{RDY}$ Input Hold Time	0		ns
$t_{h(BCLK-HOLD)}$	$\overline{HOLD}$ Input Hold Time	0		ns

NOTES:
1. Calculated according to the BCLK frequency as follows:

$$\frac{0.5 \times 10^9}{f(BCLK)} - 60 \text{[ns]}$$

2. Calculated according to the BCLK frequency as follows:

$$\frac{(n-0.5) \times 10^9}{f(BCLK)} - 60 \text{[ns]}$$ n is ”2” for 1-wait setting, “3” for 2-wait setting and “4” for 3-wait setting.

3. Calculated according to the BCLK frequency as follows:

$$\frac{(n-0.5) \times 10^9}{f(BCLK)} - 60 \text{[ns]}$$ n is “2” for 2-wait setting, “3” for 3-wait setting.

Table 5.58 Electrical Characteristics (2) (1)

Symbol	Parameter		Measuring Condition		Standard			Unit
					Min.	Typ.	Max.	
I_{CC}	Power Supply Current (V_{CC1}=V_{CC2}=4.0V to 5.5V)	In single-chip mode, the output pins are open and other pins are V_{SS}	Mask ROM	f(BCLK)=24MHz No division, PLL operation		14	20	mA
				No division, On-chip oscillation		1		mA
			Flash Memory	f(BCLK)=24MHz, No division, PLL operation		18	27	mA
				No division, On-chip oscillation		1.8		mA
			Flash Memory Program	f(BCLK)=10MHz, V_{CC1}=5.0V		15		mA
			Flash Memory Erase	f(BCLK)=10MHz, V_{CC1}=5.0V		25		mA
			Mask ROM	f(XCIN)=32kHz Low power dissipation mode, ROM (3)		25		µA
			Flash Memory	f(BCLK)=32kHz Low power dissipation mode, RAM (3)		25		µA
				f(BCLK)=32kHz Low power dissipation mode, Flash Memory (3)		420		µA
				On-chip oscillation, Wait mode		50		µA
			Mask ROM Flash Memory	f(BCLK)=32kHz Wait mode (2), Oscillation capability High		7.5		µA
				f(BCLK)=32kHz Wait mode (2), Oscillation capability Low		2.0		µA
				Stop mode Topr =25°C		2.0	6.0	µA
				Stop mode Topr =85°C			20	µA
				Stop mode Topr =125°C			TBD	µA

NOTES:
1. Referenced to V_{CC1}=V_{CC2}=4.0 to 5.5V, V_{SS} = 0V at T_{opr} = –40 to 85°C / –40 to 125°C, f(BCLK)=24MHz unless otherwise specified. T version = –40 to 85°C, V version =–40 to 125°C.
2. With one timer operated using fC32.
3. This indicates the memory in which the program to be executed exists.

$V_{CC1}=V_{CC2}=5V$

Timing Requirements
(V_{CC1} = V_{CC2} = 5V, V_{SS} = 0V, at T_{opr} = –40 to 85°C (T version) / –40 to 125°C (V version) unless otherwise specified)

Table 5.59 External Clock Input (XIN input)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
t_c	External Clock Input Cycle Time	62.5		ns
$t_{w(H)}$	External Clock Input HIGH Pulse Width	25		ns
$t_{w(L)}$	External Clock Input LOW Pulse Width	25		ns
t_r	External Clock Rise Time		15	ns
t_f	External Clock Fall Time		15	ns

$V_{CC1}=V_{CC2}=5V$

Switching Characteristics
(V_{CC1} = V_{CC2} = 5V, V_{SS} = 0V, at T_{opr} = –40 to 85°C (T version) / –40 to 125°C (V version) unless otherwise specified)

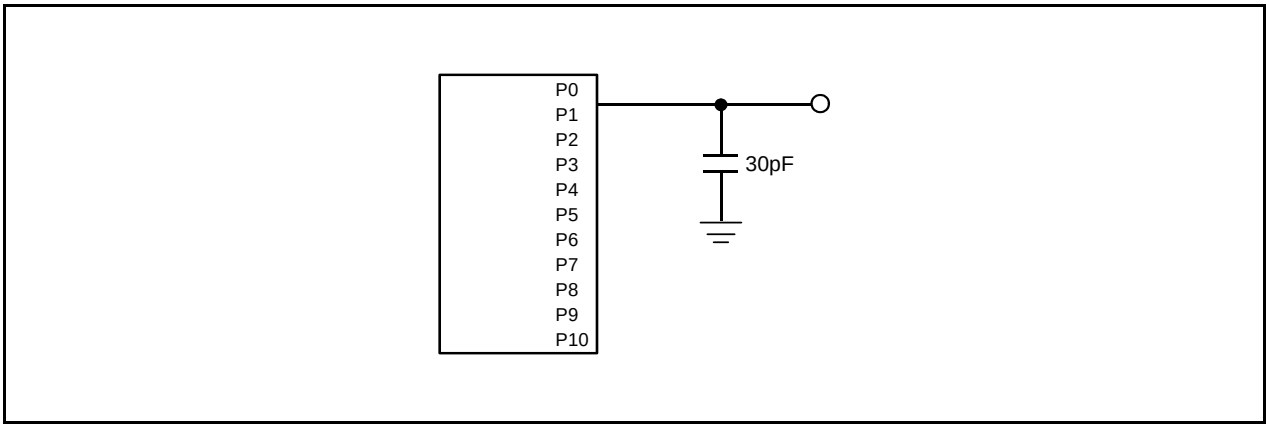


Figure 5.23 Ports P0 to P10 Measurement Circuit

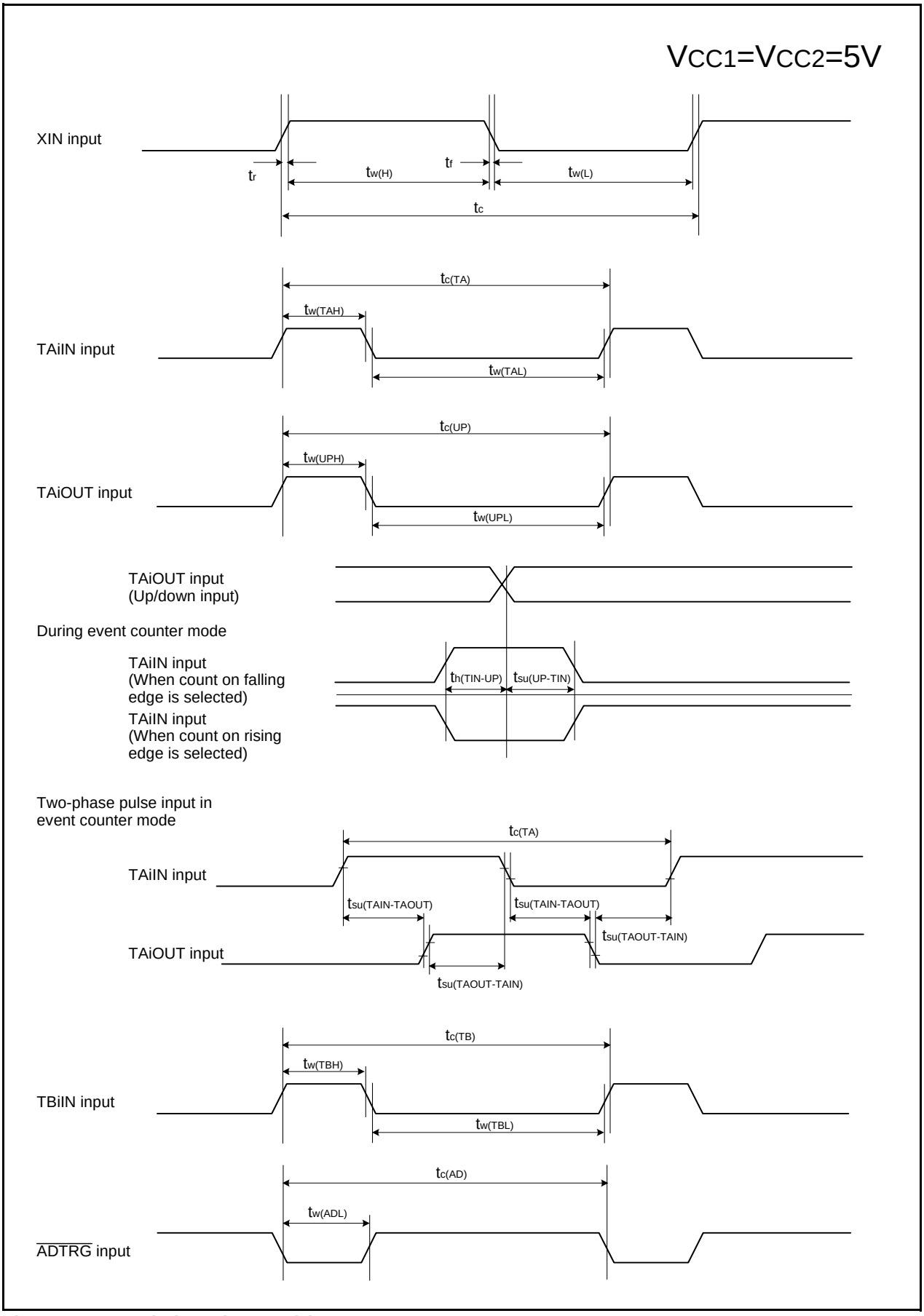


Figure 5.24 Timing Diagram (1)

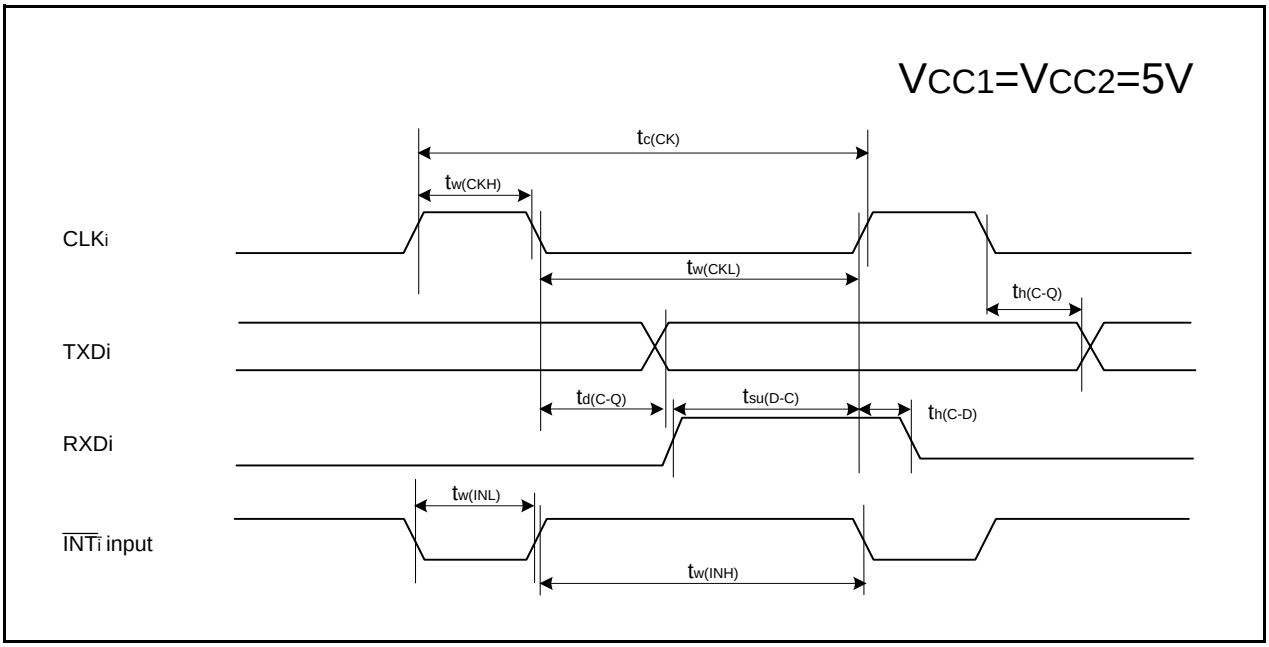


Figure 5.25 Timing Diagram (2)